TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (L^2 - π -MOSV)

2SJ402

DC-DC Converter, Relay Drive and Motor Drive Applications

• 4-V gate drive

• High forward transfer admittance : $|Y_{fs}| = 23 S \text{ (typ.)}$

• Low leakage current : I_{DSS} = -100 μA (max) (V_{DS} = -60 V)

• Enhancement mode : $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-60	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	-60	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	ID	-30	Α	
	Pulse(Note 1)	I _{DP}	-120	Α	
Drain power dissipation	n (Tc = 25°C)	P _D	100	W	
Single pulse avalanche energy (Note 2)		E _{AS}	936	mJ	
Avalanche current		I _{AR}	-30	Α	
Repetitive avalenche energy (Note 3)		E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

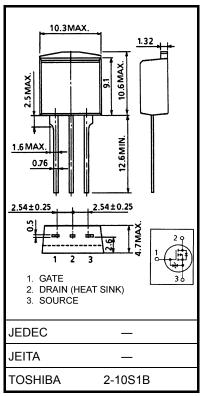
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = -50 V, T_{ch} = 25°C (initial), L = 747 μ H, R_G = 25 Ω , I_{AR} = -30 A

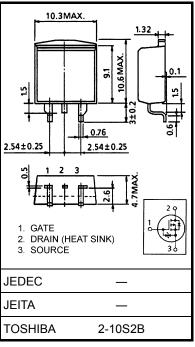
Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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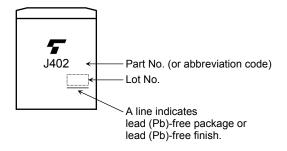
Electrical Characteristics (Ta = 25°C)

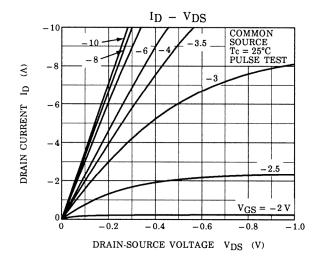
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V	_	_	-100	μA
Drain-source br	eakdown voltage	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-60	_	_	V
Gate threshold v	oltage/	V_{th}	V _{DS} = -10 V, I _D = -1 mA	-0.8	_	-2.0	V
Drain course ON register		D	V _{GS} = -4 V, I _D = -15 A	_	46	60	mΩ
Drain-source ON resistance	R _{DS} (ON)	V _{GS} = -10 V, I _D = -15 A	_	29	38		
Forward transfe	r admittance	Y _{fs}	V _{DS} = -10 V, I _D = -15 A	14	23	_	S
Input capacitano	e	C _{iss}		_	3300	_	
Reverse transfe	r capacitance	C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	460	_	pF
Output capacitance		Coss			1450	_	
Switching time	Rise time	t _r	$V_{GS} = \begin{array}{c} 0V \\ -10V \\ -1$	_	20	_	ns
	Turn-on time	t _{on}		_	25	_	
	Fall time	t _f		ı	35	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu \text{s}$	_	130	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	110	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -30 \text{ A}$		75		nC
Gate-drain ("miller") charge		Q _{gd}			35	_	

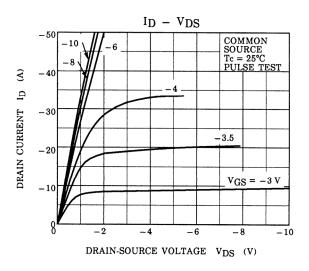
Source-Drain Ratings and Characteristics (Ta = 25°C)

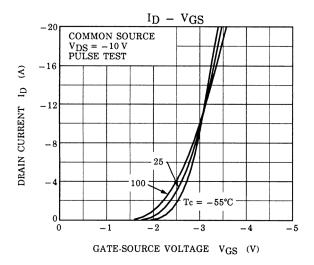
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	-30	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	-120	Α
Forward voltage (diode)	V_{DSF}	$I_{DR} = -30 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.7	V
Reverse recovery time	t _{rr}	I _{DR} = -30 A, V _{GS} = 0 V	l	100	_	ns
Reverse recovery charge	Qrr	dI_{DR} / $dt = 50 A / \mu S$		0.16	_	μC

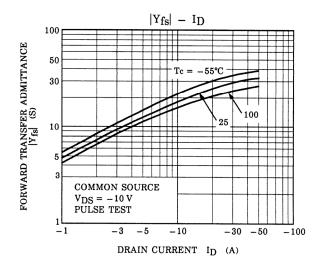
Marking

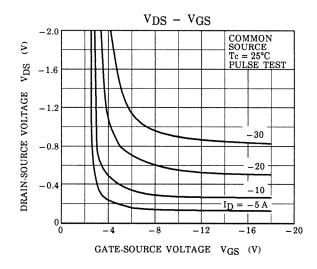


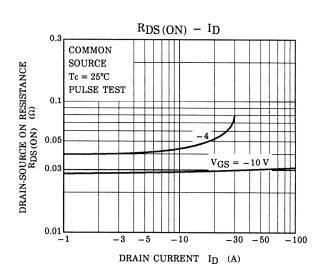




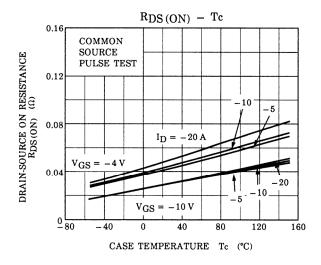


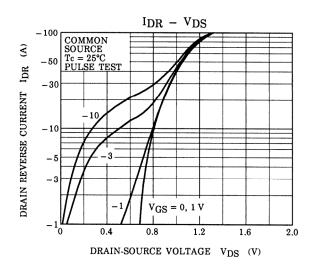


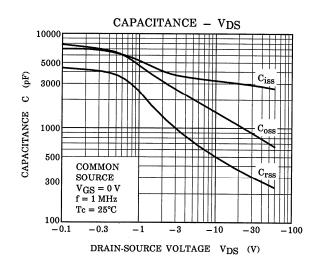


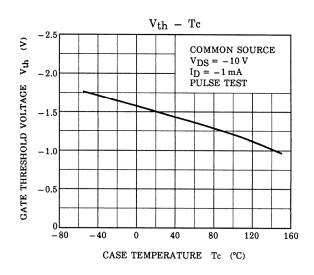


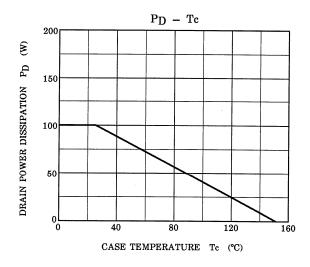
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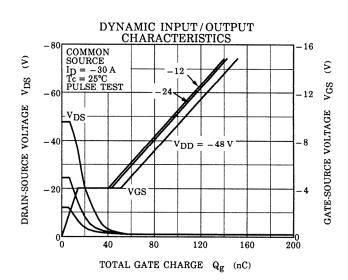


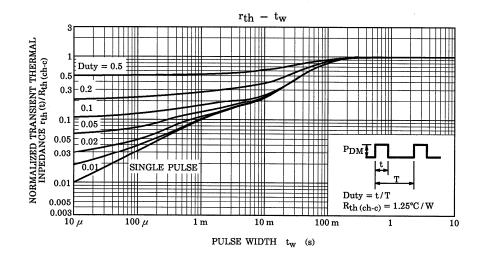


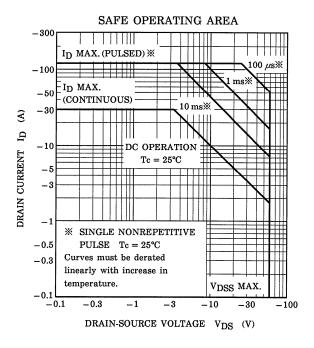


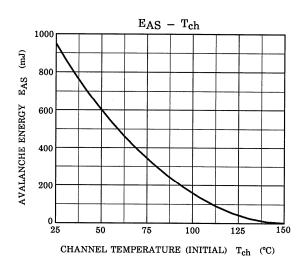


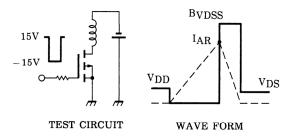












$$\begin{array}{ll} R_G \!=\! 25\Omega \\ V_{DD} \!=\! -50V, \; L \!=\! 747 \mu H \end{array} \qquad E_{AS} \!=\! \frac{1}{2} \cdot L \cdot I^2 \cdot (\frac{B_{VDSS}}{B_{VDSS} \!-\! V_{DD}})$$

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20070701-EN

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